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### Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

### Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

#### Details

Product Status	Obsolete
Number of LABs/CLBs	17110
Number of Logic Elements/Cells	362000
Total RAM Bits	19822592
Number of I/O	544
Number of Gates	-
Voltage - Supply	1.07V ~ 1.13V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	1152-BBGA, FCBGA Exposed Pad
Supplier Device Package	1152-FBGA (35x35)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/intel/5agxfb3h4f35i5">https://www.e-xfl.com/product-detail/intel/5agxfb3h4f35i5</a>

**Caution:** Conditions outside the range listed in the following table may cause permanent damage to the device. Additionally, device operation at the absolute maximum ratings for extended periods of time may have adverse effects on the device.

**Table 1-1: Absolute Maximum Ratings for Arria V Devices**

Symbol	Description	Minimum	Maximum	Unit
V <sub>CC</sub>	Core voltage power supply	–0.50	1.43	V
V <sub>CCP</sub>	Periphery circuitry, PCIe® hardIP block, and transceiver physical coding sublayer (PCS) power supply	–0.50	1.43	V
V <sub>CCPGM</sub>	Configuration pins power supply	–0.50	3.90	V
V <sub>CC_AUX</sub>	Auxiliary supply	–0.50	3.25	V
V <sub>CCBAT</sub>	Battery back-up power supply for design security volatile key register	–0.50	3.90	V
V <sub>CCPD</sub>	I/O pre-driver power supply	–0.50	3.90	V
V <sub>CCIO</sub>	I/O power supply	–0.50	3.90	V
V <sub>CCD_FPLL</sub>	Phase-locked loop (PLL) digital power supply	–0.50	1.80	V
V <sub>CCA_FPLL</sub>	PLL analog power supply	–0.50	3.25	V
V <sub>CCA_GXB</sub>	Transceiver high voltage power	–0.50	3.25	V
V <sub>CCH_GXB</sub>	Transmitter output buffer power	–0.50	1.80	V
V <sub>CCR_GXB</sub>	Receiver power	–0.50	1.50	V
V <sub>CCT_GXB</sub>	Transmitter power	–0.50	1.50	V
V <sub>CCL_GXB</sub>	Transceiver clock network power	–0.50	1.50	V
V <sub>I</sub>	DC input voltage	–0.50	3.80	V
V <sub>CC_HPS</sub>	HPS core voltage and periphery circuitry power supply	–0.50	1.43	V
V <sub>CCPD_HPS</sub>	HPS I/O pre-driver power supply	–0.50	3.90	V
V <sub>CCIO_HPS</sub>	HPS I/O power supply	–0.50	3.90	V
V <sub>CCRSTCLK_HPS</sub>	HPS reset and clock input pins power supply	–0.50	3.90	V

Symbol	Description	Minimum	Maximum	Unit
V <sub>CCPLL_HPS</sub>	HPS PLL analog power supply	–0.50	3.25	V
V <sub>CC_AUX_SHARED</sub>	HPS auxiliary power supply	–0.50	3.25	V
I <sub>OUT</sub>	DC output current per pin	–25	40	mA
T <sub>J</sub>	Operating junction temperature	–55	125	°C
T <sub>STG</sub>	Storage temperature (no bias)	–65	150	°C

### Maximum Allowed Overshoot and Undershoot Voltage

During transitions, input signals may overshoot to the voltage listed in the following table and undershoot to –2.0 V for input currents less than 100 mA and periods shorter than 20 ns.

The maximum allowed overshoot duration is specified as a percentage of high time over the lifetime of the device. A DC signal is equivalent to 100% duty cycle.

For example, a signal that overshoots to 4.00 V can only be at 4.00 V for ~15% over the lifetime of the device; for a device lifetime of 10 years, this amounts to 1.5 years.

**Table 1-2: Maximum Allowed Overshoot During Transitions for Arria V Devices**

This table lists the maximum allowed input overshoot voltage and the duration of the overshoot voltage as a percentage of device lifetime.

## Single-Ended SSTL, HSTL, and HSUL I/O Standards Signal Specifications

Table 1-16: Single-Ended SSTL, HSTL, and HSUL I/O Standards Signal Specifications for Arria V Devices

I/O Standard	$V_{IL(DC)} (V)$		$V_{IH(DC)} (V)$		$V_{IL(AC)} (V)$	$V_{IH(AC)} (V)$	$V_{OL} (V)$	$V_{OH} (V)$	$I_{OL}^{(14)} (mA)$	$I_{OH}^{(14)} (mA)$
	Min	Max	Min	Max	Max	Min	Max	Min		
SSTL-2 Class I	-0.3	$V_{REF} - 0.15$	$V_{REF} + 0.15$	$V_{CCIO} + 0.3$	$V_{REF} - 0.31$	$V_{REF} + 0.31$	$V_{TT} - 0.608$	$V_{TT} + 0.608$	8.1	-8.1
SSTL-2 Class II	-0.3	$V_{REF} - 0.15$	$V_{REF} + 0.15$	$V_{CCIO} + 0.3$	$V_{REF} - 0.31$	$V_{REF} + 0.31$	$V_{TT} - 0.81$	$V_{TT} + 0.81$	16.2	-16.2
SSTL-18 Class I	-0.3	$V_{REF} - 0.125$	$V_{REF} + 0.125$	$V_{CCIO} + 0.3$	$V_{REF} - 0.25$	$V_{REF} + 0.25$	$V_{TT} - 0.603$	$V_{TT} + 0.603$	6.7	-6.7
SSTL-18 Class II	-0.3	$V_{REF} - 0.125$	$V_{REF} + 0.125$	$V_{CCIO} + 0.3$	$V_{REF} - 0.25$	$V_{REF} + 0.25$	0.28	$V_{CCIO} - 0.28$	13.4	-13.4
SSTL-15 Class I	—	$V_{REF} - 0.1$	$V_{REF} + 0.1$	—	$V_{REF} - 0.175$	$V_{REF} + 0.175$	$0.2 \times V_{CCIO}$	$0.8 \times V_{CCIO}$	8	-8
SSTL-15 Class II	—	$V_{REF} - 0.1$	$V_{REF} + 0.1$	—	$V_{REF} - 0.175$	$V_{REF} + 0.175$	$0.2 \times V_{CCIO}$	$0.8 \times V_{CCIO}$	16	-16
SSTL-135	—	$V_{REF} - 0.09$	$V_{REF} + 0.09$	—	$V_{REF} - 0.16$	$V_{REF} + 0.16$	$0.2 \times V_{CCIO}$	$0.8 \times V_{CCIO}$	—	—
SSTL-125	—	$V_{REF} - 0.85$	$V_{REF} + 0.85$	—	$V_{REF} - 0.15$	$V_{REF} + 0.15$	$0.2 \times V_{CCIO}$	$0.8 \times V_{CCIO}$	—	—
HSTL-18 Class I	—	$V_{REF} - 0.1$	$V_{REF} + 0.1$	—	$V_{REF} - 0.2$	$V_{REF} + 0.2$	0.4	$V_{CCIO} - 0.4$	8	-8
HSTL-18 Class II	—	$V_{REF} - 0.1$	$V_{REF} + 0.1$	—	$V_{REF} - 0.2$	$V_{REF} + 0.2$	0.4	$V_{CCIO} - 0.4$	16	-16
HSTL-15 Class I	—	$V_{REF} - 0.1$	$V_{REF} + 0.1$	—	$V_{REF} - 0.2$	$V_{REF} + 0.2$	0.4	$V_{CCIO} - 0.4$	8	-8

<sup>(14)</sup> To meet the  $I_{OL}$  and  $I_{OH}$  specifications, you must set the current strength settings accordingly. For example, to meet the SSTL15CI specification (8 mA), you should set the current strength settings to 8 mA. Setting at lower current strength may not meet the  $I_{OL}$  and  $I_{OH}$  specifications in the datasheet.

I/O Standard	$V_{IL(DC)} (V)$		$V_{IH(DC)} (V)$		$V_{IL(AC)} (V)$	$V_{IH(AC)} (V)$	$V_{OL} (V)$	$V_{OH} (V)$	$I_{OL}^{(14)} (mA)$	$I_{OH}^{(14)} (mA)$
	Min	Max	Min	Max	Max	Min	Max	Min		
HSTL-15 Class II	—	$V_{REF} - 0.1$	$V_{REF} + 0.1$	—	$V_{REF} - 0.2$	$V_{REF} + 0.2$	0.4	$V_{CCIO} - 0.4$	16	-16
HSTL-12 Class I	-0.15	$V_{REF} - 0.08$	$V_{REF} + 0.08$	$V_{CCIO} + 0.15$	$V_{REF} - 0.15$	$V_{REF} + 0.15$	$0.25 \times V_{CCIO}$	$0.75 \times V_{CCIO}$	8	-8
HSTL-12 Class II	-0.15	$V_{REF} - 0.08$	$V_{REF} + 0.08$	$V_{CCIO} + 0.15$	$V_{REF} - 0.15$	$V_{REF} + 0.15$	$0.25 \times V_{CCIO}$	$0.75 \times V_{CCIO}$	16	-16
HSUL-12	—	$V_{REF} - 0.13$	$V_{REF} + 0.13$	—	$V_{REF} - 0.22$	$V_{REF} + 0.22$	$0.1 \times V_{CCIO}$	$0.9 \times V_{CCIO}$	—	—

### Differential SSTL I/O Standards

Table 1-17: Differential SSTL I/O Standards for Arria V Devices

I/O Standard	$V_{CCIO} (V)$			$V_{SWING(DC)} (V)$		$V_{X(AC)} (V)$			$V_{SWING(AC)} (V)$	
	Min	Typ	Max	Min	Max	Min	Typ	Max	Min	Max
SSTL-2 Class I, II	2.375	2.5	2.625	0.3	$V_{CCIO} + 0.6$	$V_{CCIO}/2 - 0.2$	—	$V_{CCIO}/2 + 0.2$	0.62	$V_{CCIO} + 0.6$
SSTL-18 Class I, II	1.71	1.8	1.89	0.25	$V_{CCIO} + 0.6$	$V_{CCIO}/2 - 0.175$	—	$V_{CCIO}/2 + 0.175$	0.5	$V_{CCIO} + 0.6$
SSTL-15 Class I, II	1.425	1.5	1.575	0.2	<sup>(15)</sup>	$V_{CCIO}/2 - 0.15$	—	$V_{CCIO}/2 + 0.15$	$2(V_{IH(AC)} - V_{REF})$	$2(V_{IL(AC)} - V_{REF})$
SSTL-135	1.283	1.35	1.45	0.18	<sup>(15)</sup>	$V_{CCIO}/2 - 0.15$	$V_{CCIO}/2$	$V_{CCIO}/2 + 0.15$	$2(V_{IH(AC)} - V_{REF})$	$2(V_{IL(AC)} - V_{REF})$

<sup>(14)</sup> To meet the  $I_{OL}$  and  $I_{OH}$  specifications, you must set the current strength settings accordingly. For example, to meet the SSTL15CI specification (8 mA), you should set the current strength settings to 8 mA. Setting at lower current strength may not meet the  $I_{OL}$  and  $I_{OH}$  specifications in the datasheet.

<sup>(15)</sup> The maximum value for  $V_{SWING(DC)}$  is not defined. However, each single-ended signal needs to be within the respective single-ended limits ( $V_{IH(DC)}$  and  $V_{IL(DC)}$ ).

Table 1-21: Transceiver Clocks Specifications for Arria V GX and SX Devices

Symbol/Description	Condition	Transceiver Speed Grade 4			Transceiver Speed Grade 6			Unit
		Min	Typ	Max	Min	Typ	Max	
fixedclk clock frequency	PCIe Receiver Detect	—	125	—	—	125	—	MHz
Transceiver Reconfiguration Controller IP (mgmt_clk_clk) clock frequency	—	75	—	125	75	—	125	MHz

Table 1-22: Receiver Specifications for Arria V GX and SX Devices

Symbol/Description	Condition	Transceiver Speed Grade 4			Transceiver Speed Grade 6			Unit
		Min	Typ	Max	Min	Typ	Max	
Supported I/O standards	1.5 V PCML, 2.5 V PCML, LVPECL, and LVDS							
Data rate <sup>(28)</sup>	—	611	—	6553.6	611	—	3125	Mbps
Absolute V <sub>MAX</sub> for a receiver pin <sup>(29)</sup>	—	—	—	1.2	—	—	1.2	V
Absolute V <sub>MIN</sub> for a receiver pin	—	−0.4	—	—	−0.4	—	—	V
Maximum peak-to-peak differential input voltage V <sub>ID</sub> (diff p-p) before device configuration	—	—	—	1.6	—	—	1.6	V
Maximum peak-to-peak differential input voltage V <sub>ID</sub> (diff p-p) after device configuration	—	—	—	2.2	—	—	2.2	V

<sup>(28)</sup> To support data rates lower than the minimum specification through oversampling, use the CDR in LTR mode only.<sup>(29)</sup> The device cannot tolerate prolonged operation at this absolute maximum.

Quartus Prime 1st Post Tap Pre-Emphasis Setting	Quartus Prime V <sub>OD</sub> Setting							Unit
	10 (200 mV)	20 (400 mV)	30 (600 mV)	35 (700 mV)	40 (800 mV)	45 (900 mV)	50 (1000 mV)	
16	—	—	9.56	7.73	6.49	—	—	dB
17	—	—	10.43	8.39	7.02	—	—	dB
18	—	—	11.23	9.03	7.52	—	—	dB
19	—	—	12.18	9.7	8.02	—	—	dB
20	—	—	13.17	10.34	8.59	—	—	dB
21	—	—	14.2	11.1	—	—	—	dB
22	—	—	15.38	11.87	—	—	—	dB
23	—	—	—	12.67	—	—	—	dB
24	—	—	—	13.48	—	—	—	dB
25	—	—	—	14.37	—	—	—	dB
26	—	—	—	—	—	—	—	dB
27	—	—	—	—	—	—	—	dB
28	—	—	—	—	—	—	—	dB
29	—	—	—	—	—	—	—	dB
30	—	—	—	—	—	—	—	dB
31	—	—	—	—	—	—	—	dB

**Related Information****[SPICE Models for Altera Devices](#)**

Provides the Arria V HSSI HSPICE models.

**Transceiver Compliance Specification**

The following table lists the physical medium attachment (PMA) specification compliance of all supported protocol for Arria V GX, GT, SX, and ST devices. For more information about the protocol parameter details and compliance specifications, contact your Altera Sales Representative.

Symbol	Condition	-I3, -C4			-I5, -C5			-C6			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
	SERDES factor $J \geq 8^{(76)(78)}$ , LVDS TX with RX DPA	<sup>(77)</sup>	—	1600	<sup>(77)</sup>	—	1500	<sup>(77)</sup>	—	1250	Mbps
	SERDES factor $J = 1$ to 2, Uses DDR Registers	<sup>(77)</sup>	—	<sup>(79)</sup>	<sup>(77)</sup>	—	<sup>(79)</sup>	<sup>(77)</sup>	—	<sup>(79)</sup>	Mbps
Emulated Differential I/O Standards with Three External Output Resistor Network - $f_{HSDR}$ (data rate) <sup>(80)</sup>	SERDES factor $J = 4$ to $10^{(81)}$	<sup>(77)</sup>	—	945	<sup>(77)</sup>	—	945	<sup>(77)</sup>	—	945	Mbps
Emulated Differential I/O Standards with One External Output Resistor Network - $f_{HSDR}$ (data rate) <sup>(80)</sup>	SERDES factor $J = 4$ to $10^{(81)}$	<sup>(77)</sup>	—	200	<sup>(77)</sup>	—	200	<sup>(77)</sup>	—	200	Mbps
$t_{x \text{ Jitter}}$ - True Differential I/O Standards	Total Jitter for Data Rate 600 Mbps – 1.25 Gbps	—	—	160	—	—	160	—	—	160	ps
	Total Jitter for Data Rate < 600 Mbps	—	—	0.1	—	—	0.1	—	—	0.1	UI

<sup>(78)</sup> The  $V_{CC}$  and  $V_{CCP}$  must be on a separate power layer and a maximum load of 5 pF for chip-to-chip interface.

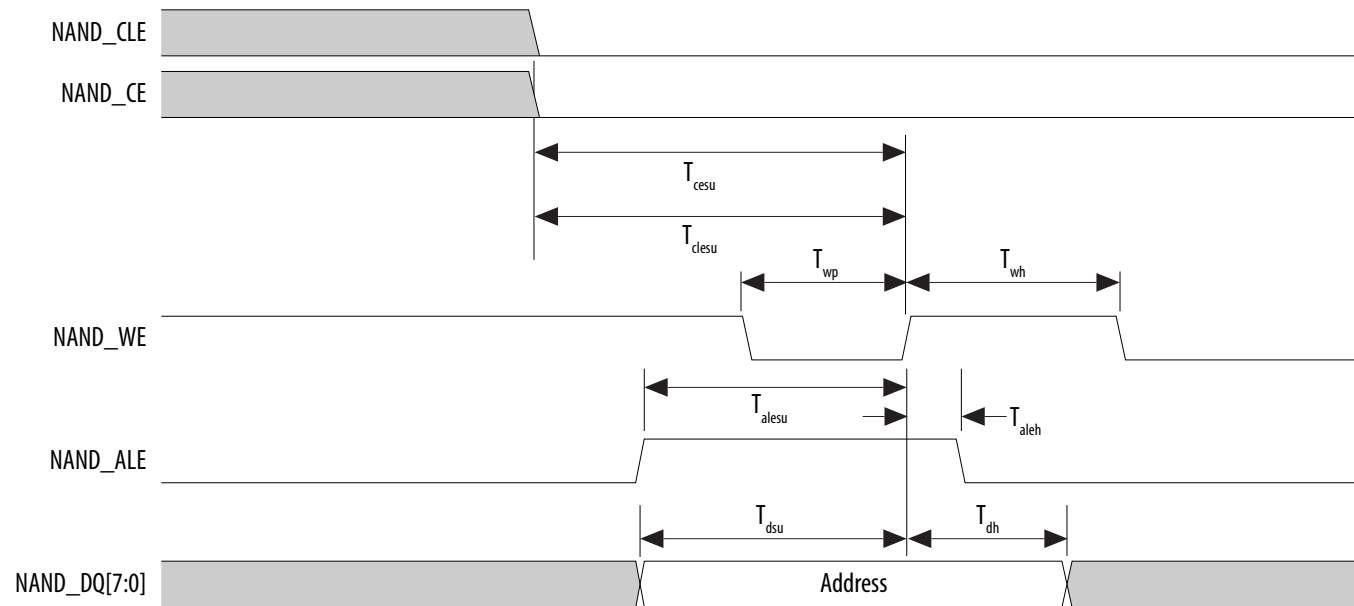
<sup>(79)</sup> The maximum ideal data rate is the SERDES factor ( $J$ ) x the PLL maximum output frequency ( $f_{OUT}$ ), provided you can close the design timing and the signal integrity simulation is clean.

<sup>(80)</sup> You must calculate the leftover timing margin in the receiver by performing link timing closure analysis. You must consider the board skew margin, transmitter channel-to-channel skew, and receiver sampling margin to determine the leftover timing margin.

<sup>(81)</sup> When using True LVDS RX channels for emulated LVDS TX channel, only serialization factors 1 and 2 are supported.



Figure 1-18: NAND Address Latch Timing Diagram



Term	Definition
$t_{\text{FALL}}$	Signal high-to-low transition time (80–20%)
$t_{\text{INCCJ}}$	Cycle-to-cycle jitter tolerance on the PLL clock input
$t_{\text{OUTPJ\_IO}}$	Period jitter on the GPIO driven by a PLL
$t_{\text{OUTPJ\_DC}}$	Period jitter on the dedicated clock output driven by a PLL
$t_{\text{RISE}}$	Signal low-to-high transition time (20–80%)
Timing Unit Interval (TUI)	The timing budget allowed for skew, propagation delays, and the data sampling window. (TUI = $1 / (\text{Receiver Input Clock Frequency Multiplication Factor}) = t_c / w$ )
$V_{\text{CM(DC)}}$	DC common mode input voltage.
$V_{\text{ICM}}$	Input common mode voltage—The common mode of the differential signal at the receiver.
$V_{\text{ID}}$	Input differential voltage swing—The difference in voltage between the positive and complementary conductors of a differential transmission at the receiver.
$V_{\text{DIF(AC)}}$	AC differential input voltage—Minimum AC input differential voltage required for switching.
$V_{\text{DIF(DC)}}$	DC differential input voltage— Minimum DC input differential voltage required for switching.
$V_{\text{IH}}$	Voltage input high—The minimum positive voltage applied to the input which is accepted by the device as a logic high.
$V_{\text{IH(AC)}}$	High-level AC input voltage
$V_{\text{IH(DC)}}$	High-level DC input voltage
$V_{\text{IL}}$	Voltage input low—The maximum positive voltage applied to the input which is accepted by the device as a logic low.
$V_{\text{IL(AC)}}$	Low-level AC input voltage
$V_{\text{IL(DC)}}$	Low-level DC input voltage
$V_{\text{OCM}}$	Output common mode voltage—The common mode of the differential signal at the transmitter.
$V_{\text{OD}}$	Output differential voltage swing—The difference in voltage between the positive and complementary conductors of a differential transmission line at the transmitter.
$V_{\text{SWING}}$	Differential input voltage
$V_{\text{X}}$	Input differential cross point voltage

Date	Version	Changes
June 2015	2015.06.16	<ul style="list-style-type: none"> <li>Added the supported data rates for the following output standards using true LVDS output buffer types in the High-Speed I/O Specifications for Arria V Devices table: <ul style="list-style-type: none"> <li>True RSDS output standard: data rates of up to 360 Mbps</li> <li>True mini-LVDS output standard: data rates of up to 400 Mbps</li> </ul> </li> <li>Added note in the condition for Transmitter—Emulated Differential I/O Standards <math>f_{\text{HSDR}}</math> data rate parameter in the High-Speed I/O Specifications for Arria V Devices table. Note: When using True LVDS RX channels for emulated LVDS TX channel, only serialization factors 1 and 2 are supported.</li> <li>Changed Queued Serial Peripheral Interface (QSPI) to Quad Serial Peripheral Interface (SPI) Flash.</li> <li>Updated <math>T_h</math> location in I<sup>2</sup>C Timing Diagram.</li> <li>Updated <math>T_{\text{wp}}</math> location in NAND Address Latch Timing Diagram.</li> <li>Corrected the unit for <math>t_{\text{DH}}</math> from ns to s in FPP Timing Parameters When DCLK-to-DATA[] Ratio is &gt;1 for Arria V Devices table.</li> <li>Updated the maximum value for <math>t_{\text{CO}}</math> from 4 ns to 2 ns in AS Timing Parameters for AS <math>\times 1</math> and <math>\times 4</math> Configurations in Arria V Devices table.</li> <li>Moved the following timing diagrams to the Configuration, Design Security, and Remote System Upgrades in Arria V Devices chapter. <ul style="list-style-type: none"> <li>FPP Configuration Timing Waveform When DCLK-to-DATA[] Ratio is 1</li> <li>FPP Configuration Timing Waveform When DCLK-to-DATA[] Ratio is &gt;1</li> <li>AS Configuration Timing Waveform</li> <li>PS Configuration Timing Waveform</li> </ul> </li> </ul>

Symbol	Description	Minimum <sup>(118)</sup>	Typical	Maximum <sup>(118)</sup>	Unit
V <sub>CCR_GXBL</sub> <sup>(121)</sup>	Receiver analog power supply (left side)	0.82	0.85	0.88	V
		0.97	1.0	1.03	
		1.03	1.05	1.07	
V <sub>CCR_GXBR</sub> <sup>(121)</sup>	Receiver analog power supply (right side)	0.82	0.85	0.88	V
		0.97	1.0	1.03	
		1.03	1.05	1.07	
V <sub>CCT_GXBL</sub> <sup>(121)</sup>	Transmitter analog power supply (left side)	0.82	0.85	0.88	V
		0.97	1.0	1.03	
		1.03	1.05	1.07	
V <sub>CCT_GXBR</sub> <sup>(121)</sup>	Transmitter analog power supply (right side)	0.82	0.85	0.88	V
		0.97	1.0	1.03	
		1.03	1.05	1.07	
V <sub>CCH_GXBL</sub>	Transmitter output buffer power supply (left side)	1.425	1.5	1.575	V
V <sub>CCH_GXBR</sub>	Transmitter output buffer power supply (right side)	1.425	1.5	1.575	V

<sup>(118)</sup> This value describes the budget for the DC (static) power supply tolerance and does not include the dynamic tolerance requirements. Refer to the PDN tool for the additional budget for the dynamic tolerance requirements.

<sup>(121)</sup> This supply must be connected to 1.0 V if the transceiver is configured at a data rate > 6.5 Gbps, and to 1.05 V if configured at a data rate > 10.3 Gbps when DFE is used. For data rate up to 6.5 Gbps, you can connect this supply to 0.85 V.

Symbol	Description	Conditions	Calibration Accuracy		Unit
			C3, I3L	C4, I4	
25-Ω R <sub>S</sub>	Internal series termination with calibration (25-Ω setting)	V <sub>CCIO</sub> = 3.0, 2.5, 1.8, 1.5, 1.2 V	±15	±15	%
50-Ω R <sub>S</sub>	Internal series termination with calibration (50-Ω setting)	V <sub>CCIO</sub> = 3.0, 2.5, 1.8, 1.5, 1.2 V	±15	±15	%
34-Ω and 40-Ω R <sub>S</sub>	Internal series termination with calibration (34-Ω and 40-Ω setting)	V <sub>CCIO</sub> = 1.5, 1.35, 1.25, 1.2 V	±15	±15	%
48-Ω, 60-Ω, 80-Ω, and 240-Ω R <sub>S</sub>	Internal series termination with calibration (48-Ω, 60-Ω, 80-Ω, and 240-Ω setting)	V <sub>CCIO</sub> = 1.2 V	±15	±15	%
50-Ω R <sub>T</sub>	Internal parallel termination with calibration (50-Ω setting)	V <sub>CCIO</sub> = 2.5, 1.8, 1.5, 1.2 V	-10 to +40	-10 to +40	%
20-Ω, 30-Ω, 40-Ω, 60-Ω, and 120-Ω R <sub>T</sub>	Internal parallel termination with calibration (20-Ω, 30-Ω, 40-Ω, 60-Ω, and 120-Ω setting)	V <sub>CCIO</sub> = 1.5, 1.35, 1.25 V	-10 to +40	-10 to +40	%
60-Ω and 120-Ω R <sub>T</sub>	Internal parallel termination with calibration (60-Ω and 120-Ω setting)	V <sub>CCIO</sub> = 1.2	-10 to +40	-10 to +40	%
25-Ω R <sub>S_left_shift</sub>	Internal left shift series termination with calibration (25-Ω R <sub>S_left_shift</sub> setting)	V <sub>CCIO</sub> = 3.0, 2.5, 1.8, 1.5, 1.2 V	±15	±15	%

Table 2-11: OCT Without Calibration Resistance Tolerance Specifications for Arria V GZ Devices

Symbol	Description	Conditions	Resistance Tolerance		Unit
			C3, I3L	C4, I4	
25-Ω R, 50-Ω R <sub>S</sub>	Internal series termination without calibration (25-Ω setting)	V <sub>CCIO</sub> = 3.0 and 2.5 V	±40	±40	%

## Hot Socketing

Table 2-14: Hot Socketing Specifications for Arria V GZ Devices

Symbol	Description	Maximum
$I_{IOPIN} (DC)$	DC current per I/O pin	300 $\mu A$
$I_{IOPIN} (AC)$	AC current per I/O pin	8 mA <sup>(124)</sup>
$I_{XCVR-TX} (DC)$	DC current per transceiver transmitter pin	100 mA
$I_{XCVR-RX} (DC)$	DC current per transceiver receiver pin	50 mA

## Internal Weak Pull-Up Resistor

Table 2-15: Internal Weak Pull-Up Resistor for Arria V GZ Devices

All I/O pins have an option to enable the weak pull-up resistor except the configuration, test, and JTAG pins. The internal weak pull-down feature is only available for the JTAG  $TCK$  pin. The typical value for this internal weak pull-down resistor is approximately 25 k $\Omega$ .

Symbol	Description	$V_{CCIO}$ Conditions (V) <sup>(125)</sup>	Value <sup>(126)</sup>	Unit
$R_{PU}$	Value of the I/O pin pull-up resistor before and during configuration, as well as user mode if you enable the programmable pull-up resistor option.	3.0 $\pm 5\%$	25	k $\Omega$
		2.5 $\pm 5\%$	25	k $\Omega$
		1.8 $\pm 5\%$	25	k $\Omega$
		1.5 $\pm 5\%$	25	k $\Omega$
		1.35 $\pm 5\%$	25	k $\Omega$
		1.25 $\pm 5\%$	25	k $\Omega$
		1.2 $\pm 5\%$	25	k $\Omega$

<sup>(124)</sup> The I/O ramp rate is 10 ns or more. For ramp rates faster than 10 ns,  $|I_{IOPIN}| = C dv/dt$ , in which C is the I/O pin capacitance and  $dv/dt$  is the slew rate.

<sup>(125)</sup> The pin pull-up resistance values may be lower if an external source drives the pin higher than  $V_{CCIO}$ .

<sup>(126)</sup> These specifications are valid with a  $\pm 10\%$  tolerance to cover changes over PVT.

Symbol/Description	Conditions	Transceiver Speed Grade 2			Transceiver Speed Grade 3			Unit
		Min	Typ	Max	Min	Typ	Max	
Supported data range	—	600	—	3250/ 3125 <sup>(158)</sup>	600	—	3250/ 3125 <sup>(158)</sup>	Mbps
$t_{\text{pll\_powerdown}}$ <sup>(159)</sup>	—	1	—	—	1	—	—	μs
$t_{\text{pll\_lock}}$ <sup>(160)</sup>	—	—	—	10	—	—	10	μs

**Related Information**[Arria V Device Overview](#)

For more information about device ordering codes.

**Clock Network Data Rate****Table 2-29: Clock Network Maximum Data Rate Transmitter Specifications**

Valid data rates below the maximum specified in this table depend on the reference clock frequency and the PLL counter settings. Check the MegaWizard message during the PHY IP instantiation.

Clock Network	ATX PLL			CMU PLL <sup>(161)</sup>			fPLL		
	Non-bonded Mode (Gbps)	Bonded Mode (Gbps)	Channel Span	Non-bonded Mode (Gbps)	Bonded Mode (Gbps)	Channel Span	Non-bonded Mode (Gbps)	Bonded Mode (Gbps)	Channel Span
x1 <sup>(162)</sup>	12.5	—	6	12.5	—	6	3.125	—	3
x6 <sup>(162)</sup>	—	12.5	6	—	12.5	6	—	3.125	6
x6 PLL Feedback <sup>(163)</sup>	—	12.5	Side-wide	—	12.5	Side-wide	—	—	—

<sup>(158)</sup> When you use fPLL as a TXPLL of the transceiver.

<sup>(159)</sup>  $t_{\text{pll\_powerdown}}$  is the PLL powerdown minimum pulse width.

<sup>(160)</sup>  $t_{\text{pll\_lock}}$  is the time required for the transmitter CMU/ATX PLL to lock to the input reference clock frequency after coming out of reset.

<sup>(161)</sup> ATX PLL is recommended at 8 Gbps and above data rates for improved jitter performance.

<sup>(162)</sup> Channel span is within a transceiver bank.

<sup>(163)</sup> Side-wide channel bonding is allowed up to the maximum supported by the PHY IP.

Clock Network	ATX PLL			CMU PLL <sup>(161)</sup>			fPLL		
	Non-bonded Mode (Gbps)	Bonded Mode (Gbps)	Channel Span	Non-bonded Mode (Gbps)	Bonded Mode (Gbps)	Channel Span	Non-bonded Mode (Gbps)	Bonded Mode (Gbps)	Channel Span
xN (PCIe)	—	8.0	8	—	5.0	8	—	—	—
xN (Native PHY IP)	8.0	8.0	Up to 13 channels above and below PLL	7.99	7.99	Up to 13 channels above and below PLL	3.125	3.125	Up to 13 channels above and below PLL
	—	8.01 to 9.8304	Up to 7 channels above and below PLL						

## Standard PCS Data Rate

**Table 2-30: Standard PCS Approximate Maximum Date Rate (Gbps) for Arria V GZ Devices**

The maximum data rate is also constrained by the transceiver speed grade. Refer to the “Commercial and Industrial Speed Grade Offering for Arria V GZ Devices” table for the transceiver speed grade.

Mode <sup>(164)</sup>	Transceiver Speed Grade	PMA Width	20	20	16	16	10	10	8	8
		PCS/Core Width	40	20	32	16	20	10	16	8
FIFO	2	C3, I3L core speed grade	9.9	9	7.84	7.2	5.3	4.7	4.24	3.76
	3	C4, I4 core speed grade	8.8	8.2	7.2	6.56	4.8	4.3	3.84	3.44

<sup>(161)</sup> ATX PLL is recommended at 8 Gbps and above data rates for improved jitter performance.

<sup>(164)</sup> The Phase Compensation FIFO can be configured in FIFO mode or register mode. In the FIFO mode, the pointers are not fixed, and the latency can vary. In the register mode the pointers are fixed for low latency.



Symbol	Conditions	C3, I3L			C4, I4			Unit
		Min	Typ	Max	Min	Typ	Max	
True Differential I/O Standards - $f_{\text{HSDRDP A}}$ (data rate)	SERDES factor J = 3 to 10 (192), (193), (194), (195), (196), (197)	150	—	1250	150	—	1050	Mbps
	SERDES factor J $\geq 4$ LVDS RX with DPA (193), (195), (196), (197)	150	—	1600	150	—	1250	Mbps
	SERDES factor J = 2, uses DDR Registers	(198)	—	(199)	(198)	—	(199)	Mbps
	SERDES factor J = 1, uses SDR Register	(198)	—	(199)	(198)	—	(199)	Mbps
$f_{\text{HSDR}}$ (data rate)	SERDES factor J = 3 to 10	(198)	—	(200)	(198)	—	(200)	Mbps
	SERDES factor J = 2, uses DDR Registers	(198)	—	(199)	(198)	—	(199)	Mbps
	SERDES factor J = 1, uses SDR Register	(198)	—	(199)	(198)	—	(199)	Mbps

(192) The  $F_{\text{MAX}}$  specification is based on the fast clock used for serial data. The interface  $F_{\text{MAX}}$  is also dependent on the parallel clock domain which is design dependent and requires timing analysis.

(193) Arria V GZ RX LVDS will need DPA. For Arria V GZ TX LVDS, the receiver side component must have DPA.

(194) Arria V GZ LVDS serialization and de-serialization factor needs to be x4 and above.

(195) Requires package skew compensation with PCB trace length.

(196) Do not mix single-ended I/O buffer within LVDS I/O bank.

(197) Chip-to-chip communication only with a maximum load of 5 pF.

(198) The minimum specification depends on the clock source (for example, the PLL and clock pin) and the clock routing resource (global, regional, or local) that you use. The I/O differential buffer and input register do not have a minimum toggle rate.

(199) The maximum ideal data rate is the SERDES factor (J) x the PLL maximum output frequency ( $f_{\text{OUT}}$ ) provided you can close the design timing and the signal integrity simulation is clean.

(200) You can estimate the achievable maximum data rate for non-DPA mode by performing link timing closure analysis. You must consider the board skew margin, transmitter delay margin, and receiver sampling margin to determine the maximum data rate supported.

## DLL Range Specifications

**Table 2-47: DLL Range Specifications for Arria V GZ Devices**

Arria V GZ devices support memory interface frequencies lower than 300 MHz, although the reference clock that feeds the DLL must be at least 300 MHz. To support interfaces below 300 MHz, multiply the reference clock feeding the DLL to ensure the frequency is within the supported range of the DLL.

Parameter	C3, I3L	C4, I4	Unit
DLL operating frequency range	300 – 890	300 – 890	MHz

## DQS Logic Block Specifications

**Table 2-48: DQS Phase Offset Delay Per Setting for Arria V GZ Devices**

The typical value equals the average of the minimum and maximum values.

The delay settings are linear with a cumulative delay variation of 40 ps for all speed grades. For example, when using a –3 speed grade and applying a 10-phase offset setting to a 90° phase shift at 400 MHz, the expected average cumulative delay is  $[625 \text{ ps} + (10 \times 11 \text{ ps}) \pm 20 \text{ ps}] = 735 \text{ ps} \pm 20 \text{ ps}$ .

Speed Grade	Min	Max	Unit
C3, I3L	8	15	ps
C4, I4	8	16	ps

**Table 2-49: DQS Phase Shift Error Specification for DLL-Delayed Clock ( $t_{\text{DQS\_PSERR}}$ ) for Arria V GZ Devices**

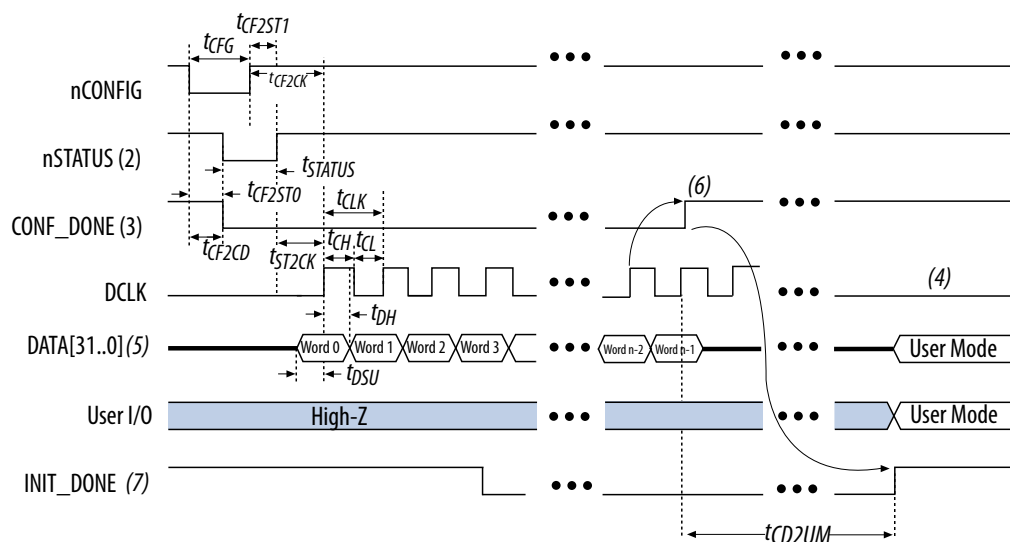
This error specification is the absolute maximum and minimum error. For example, skew on three DQS delay buffers in a –3 speed grade is  $\pm 84 \text{ ps}$  or  $\pm 42 \text{ ps}$ .

Number of DQS Delay Buffers	C3, I3L	C4, I4	Unit
1	30	32	ps
2	60	64	ps
3	90	96	ps

## FPP Configuration Timing when DCLK to DATA[] = 1

Figure 2-7: FPP Configuration Timing Waveform When the DCLK-to-DATA[] Ratio is 1

Timing waveform for FPP configuration when using a MAX<sup>®</sup> II or MAX V device as an external host.



### Notes:

1. The beginning of this waveform shows the device in user mode. In user mode, nCONFIG, nSTATUS, and CONF\_DONE are at logic-high levels. When nCONFIG is pulled low, a reconfiguration cycle begins.
2. After power-up, the Arria V GZ device holds nSTATUS low for the time of the POR delay.
3. After power-up, before and during configuration, CONF\_DONE is low.
4. Do not leave DCLK floating after configuration. DCLK is ignored after configuration is complete. It can toggle high or low if required.
5. For FPP  $\times 16$ , use DATA[15..0]. For FPP  $\times 8$ , use DATA[7..0]. DATA[31..0] are available as a user I/O pin after configuration. The state of this pin depends on the dual-purpose pin settings.
6. To ensure a successful configuration, send the entire configuration data to the Arria V GZ device. CONF\_DONE is released high when the Arria V GZ device receives all the configuration data successfully. After CONF\_DONE goes high, send two additional falling edges on DCLK to begin initialization and enter user mode.
7. After the option bit to enable the INIT\_DONE pin is configured into the device, the INIT\_DONE goes low.

Symbol	Parameter	Minimum	Maximum	Unit
$t_{CD2CU}$	CONF_DONE high to CLKUSR enabled	$4 \times \text{maximum DCLK period}$	—	—
$t_{CD2UMC}$	CONF_DONE high to user mode with CLKUSR option on	$t_{CD2CU} + (8576 \times \text{CLKUSR period})$ (209)	—	—

**Related Information**

- [DCLK-to-DATA\[\] Ratio \(r\) for FPP Configuration](#) on page 2-57
- [Configuration, Design Security, and Remote System Upgrades in Arria V Devices](#)

<sup>(208)</sup> The minimum and maximum numbers apply only if you chose the internal oscillator as the clock source for initializing the device.

<sup>(209)</sup> To enable the CLKUSR pin as the initialization clock source and to obtain the maximum frequency specification on these pins, refer to the “Initialization” section of the *Configuration, Design Security, and Remote System Upgrades in Arria V Devices* chapter.

**Table 2-57: FPP Timing Parameters for Arria V GZ Devices When the DCLK-to-DATA[] Ratio is >1**

Use these timing parameters when you use the decompression and design security features.

Symbol	Parameter	Minimum	Maximum	Unit
$t_{CF2CD}$	nCONFIG low to CONF_DONE low	—	600	ns
$t_{CF2ST0}$	nCONFIG low to nSTATUS low	—	600	ns
$t_{CFG}$	nCONFIG low pulse width	2	—	$\mu$ s
$t_{STATUS}$	nSTATUS low pulse width	268	1,506 <sup>(210)</sup>	$\mu$ s
$t_{CF2ST1}$	nCONFIG high to nSTATUS high	—	1,506 <sup>(211)</sup>	$\mu$ s
$t_{CF2CK}$ <sup>(212)</sup>	nCONFIG high to first rising edge on DCLK	1,506	—	$\mu$ s
$t_{ST2CK}$ <sup>(212)</sup>	nSTATUS high to first rising edge of DCLK	2	—	$\mu$ s
$t_{DSU}$	DATA[] setup time before rising edge on DCLK	5.5	—	ns
$t_{DH}$	DATA[] hold time after rising edge on DCLK	$N - 1/f_{DCLK}$ <sup>(213)</sup>	—	s
$t_{CH}$	DCLK high time	$0.45 \times 1/f_{MAX}$	—	s
$t_{CL}$	DCLK low time	$0.45 \times 1/f_{MAX}$	—	s
$t_{CLK}$	DCLK period	$1/f_{MAX}$	—	s
$f_{MAX}$	DCLK frequency (FPP $\times 8/\times 16$ )	—	125	MHz
	DCLK frequency (FPP $\times 32$ )	—	100	MHz
$t_R$	Input rise time	—	40	ns
$t_F$	Input fall time	—	40	ns
$t_{CD2UM}$	CONF_DONE high to user mode <sup>(214)</sup>	175	437	$\mu$ s

<sup>(210)</sup> You can obtain this value if you do not delay configuration by extending the nCONFIG or nSTATUS low pulse width.

<sup>(211)</sup> You can obtain this value if you do not delay configuration by externally holding the nSTATUS low.

<sup>(212)</sup> If nSTATUS is monitored, follow the  $t_{ST2CK}$  specification. If nSTATUS is not monitored, follow the  $t_{CF2CK}$  specification.

<sup>(213)</sup> N is the DCLK-to-DATA ratio and  $f_{DCLK}$  is the DCLK frequency the system is operating.

<sup>(214)</sup> The minimum and maximum numbers apply only if you use the internal oscillator as the clock source for initializing the device.